

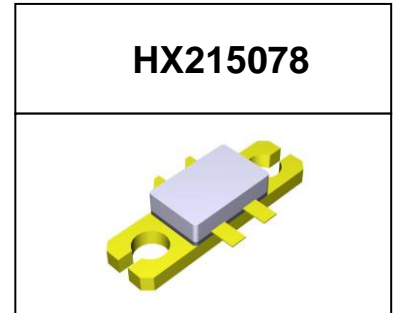
**Description**

The HX215078 is a 70-watt, unmatched, push pull LDMOS FETs, designed for Wide-band and Mobile radio applications with frequencies under 1500MHz. It can be used in Class AB/B and Class C for all typical modulation formats.

- Typical Performance (On fixture with device soldered):

$V_{DD} = 28$  Volts,  $I_{DQ} = 500$  mA, CW.

Frequency	Gp (dB)	P <sub>-1dB</sub> (W)	$\eta_D@P_{-1}$ (%)
1000 MHz	20	70	60



**Features**

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

**Suitable Applications**

- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 118 -140MHz (Avionics)
- 136-174MHz (Commercial ground communication)
- 160-230MHz (TV VHF III)
- 30-512MHz (Jammer, Ground/Air communication)
- 470-860MHz (TV UHF)

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DSS}$	+95	Vdc
Gate--Source Voltage	$V_{GS}$	-10 to +10	Vdc
Operating Voltage	$V_{DD}$	+40	Vdc
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Case Operating Temperature	$T_c$	+150	°C
Operating Junction Temperature	$T_J$	+225	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_C = 85^\circ\text{C}$ , $T_J = 200^\circ\text{C}$ , DC test	$R_{\theta JC}$	0.7	°C/W

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22--A114)	Class 2

**Table 4. Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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**DC Characteristics (per half section)**

Drain-Source Voltage $V_{GS}=0, I_{DS}=1.0mA$	$V_{(BR)DSS}$	90	95		V
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28 V, V_{GS} = 0 V$ )	$I_{DSS}$	---	---	1	$\mu A$
Gate--Source Leakage Current ( $V_{GS} = 9 V, V_{DS} = 0 V$ )	$I_{GSS}$	---	---	1	$\mu A$
Gate Threshold Voltage ( $V_{DS} = 28V, I_D = 600 \mu A$ )	$V_{GS(th)}$	---	2.11	---	V
Common Source Input Capacitance ( $V_{GS} = 0V, V_{DS} =28 V, f = 1 MHz$ )	$C_{ISS}$		34.1		pF
Common Source Output Capacitance ( $V_{GS} = 0V, V_{DS} =28 V, f = 1 MHz$ )	$C_{OSS}$		11.2		pF
Common Source Feedback Capacitance ( $V_{GS} = 0V, V_{DS} =28 V, f = 1 MHz$ )	$C_{RSS}$		0.9		pF
Common Source Input Capacitance ( $V_{GS} = 0V, V_{DS} =40 V, f = 1 MHz$ )	$C_{ISS}$		34.1		pF
Common Source Output Capacitance ( $V_{GS} = 0V, V_{DS} =40 V, f = 1 MHz$ )	$C_{OSS}$		9.7		pF
Common Source Feedback Capacitance ( $V_{GS} = 0V, V_{DS} =40 V, f = 1 MHz$ )	$C_{RSS}$		0.86		pF

**Functional Tests** (On Demo Test Fixture, 50 ohm system)  $V_{DD} = 28 Vdc, I_{DQ} = 500 mA, f = 1000 MHz$ , CW Signal Measurements.

Power Gain	$G_p$		20		dB
Drain Efficiency@P1dB	$\eta_D$		60		%
1 dB Compression Point	$P_{-1dB}$		70		W
Input Return Loss	IRL		-10		dB

**Load Mismatch (In Test Fixture, 50 ohm system):**  $V_{DD} = 28 Vdc, I_{DQ} = 500 mA, f = 1000 MHz$

VSWR 10:1 at 20W pulse CW Output Power	No Device Degradation
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### Package Outline

Flanged ceramic package; 2 mounting holes; 4 leads

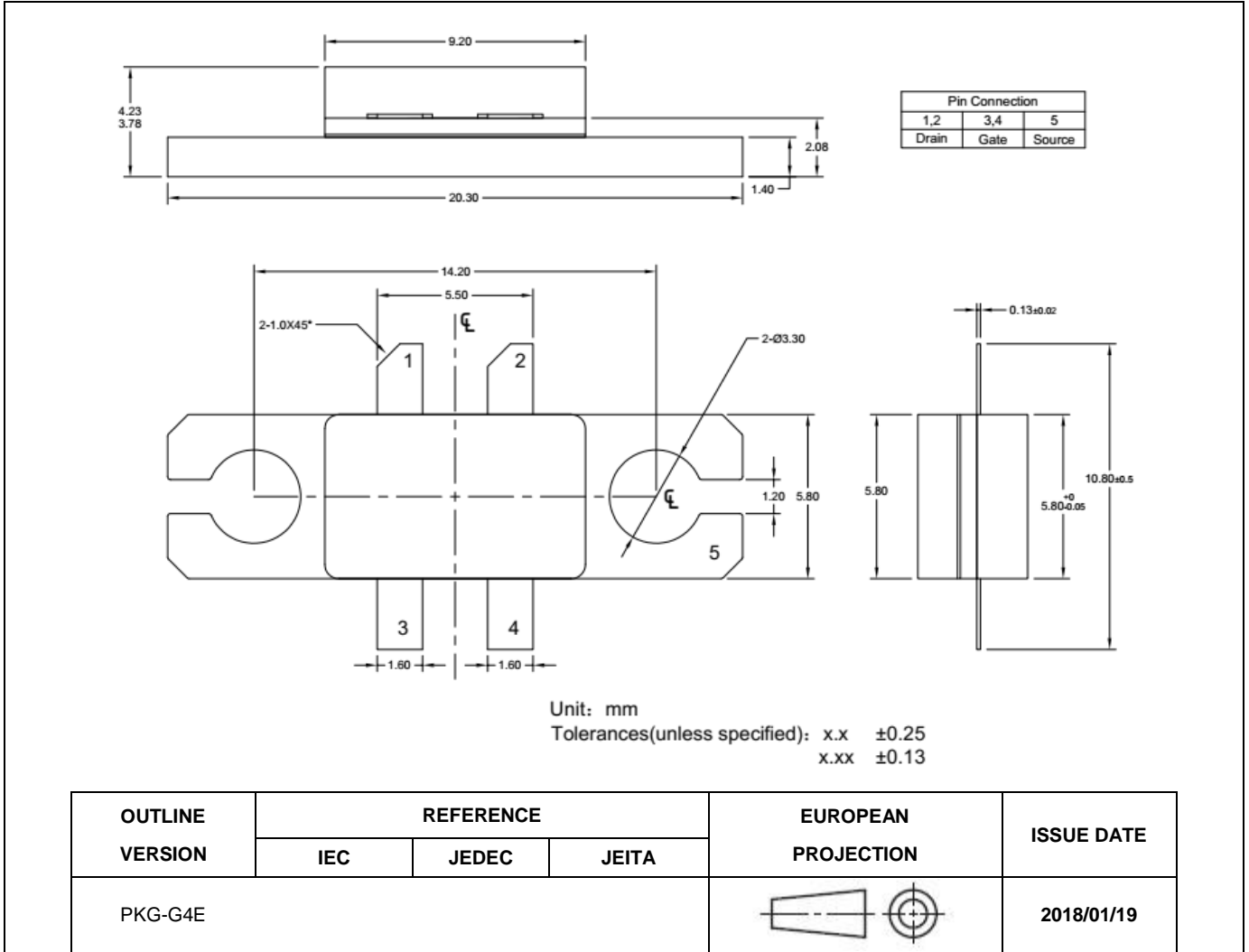


Figure 1. Package Outline PKG-G4E